

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination NISHIMURA, NAOKI	
		Examiner Jarrett J. Stark	Art Unit 2823	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,134,485	10-2000	Tanielian et al.	701/14
*	B	US-6,008,776	12-1999	Yarbrough et al.	343/853
*	C	US-6,396,450	05-2002	Gilbert, Roland	343/756
*	D	US-6,388,631	05-2002	Livingston et al.	343/767
*	E	US-6,566,255	05-2003	Ito, Masataka	438/660
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*	Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)	
	U	Yun, C.H., Cheung, N.W. Thermal and Mechanical Separations of silicon layers from Hydrogen Pattern-Implanted Wafers, Journal of Electronic Materials, Vol. 30, No 8, 2001
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.